

MicroTech 2023 Annual Conference

Thursday 30th March 2023

“Advanced Packaging and Technology Trends”

CALL FOR ABSTRACTS

IMAPS-UK Technical Conference



Venue: University of Strathclyde, Glasgow, Scotland

MicroTech 2023 is the **Annual IMAPS-UK Conference** which, this year, focuses on the key challenges associated with **Advanced Packaging and Technology Trends**. This **Face to Face Conference** combines invited **Keynotes** and **Presentations** from leading Industrial Companies and Research Institutions.

MicroTech 2023 will address the themes such as **market analysis** including current and future **supply chain** requirements, providing examples of the implementation of advanced packaging technologies in challenging applications, the development of **sustainable materials and processes** and latest advances in the assessment of quality and reliability. **Advanced Packaging Technologies** will not only be expected to demonstrate **enhanced performance**, but also **improved efficiency, reduced thermal impact** and **overall life cycle** cost benefits.

IMAPS-UK invites **Abstracts** which describe the latest **advanced packaging technologies, sustainable materials & processes, challenging applications and quality/reliability aspects** which will have a significant impact on electronics of the future.

MicroTech 2023 aims to provide the **Delegates** with an opportunity to learn from and network with **leading Industry Experts** as they share their experiences, developments and opportunities.

Organising Committee

Event Chair:	Andrew Holland - RFMOD	
Organising Committee:	David King – Alter Technology Eamonn Redmond - Inseto, Scott Wood – Accelonix Martin Wickham - NPL	Secretariat: Steve Riches





Instructions for participation

We invite submission of abstracts in the following areas:

Research and Development Papers: These will describe high-impact academic research relating to the conference topics.

Technical Presentations: Technical presentations showcasing in-production or pre-production techniques relating to the conference topics.

Current/Future trends: Presentations demonstrating how markets related to the main conference topics are developing over time.

All abstracts received by the submission deadline will be evaluated by the technical committee. Abstracts covering a balanced range of the main conference topics will be selected and invited to provide an **Oral Presentation** (20mins + 5 mins questions) during the conference.

Conference Topics – Advanced Packaging and Technology Trends

Challenging Applications	Advanced Packaging Technologies	Sustainable Materials and Processes	Quality and Reliability
<ul style="list-style-type: none"> • High and Low Temperature Electronics • Medical • Renewables • Automotive • Aerospace 	<ul style="list-style-type: none"> • Chiplets • Quantum Computing • Photonics/Quantum • Power Electronics • MEMS and Sensors • Heterogeneous Integration • System in Package (SIP) 	<ul style="list-style-type: none"> • Life Cycle Assessment • Circular Economy • E-waste/WEEE • Thermal and Electrical Efficiency • Degradable Electronics • Sustainable and Critical Raw Materials • Reduced Emissions 	<ul style="list-style-type: none"> • Reliability Test Development • Lifetime Prediction • Failure Modes • Failure Analysis Techniques • Modelling and Simulation

Those wishing to present their work at MicroTech 2023 should submit an abstract of 200-300 words, electronically to: office@imaps.org.uk by the deadline of **Friday 6th January 2023**.

Deadlines

Abstract submission (200-300 words)	Friday 6 th January 2023
Acceptance of Abstracts for Oral Presentation	Friday 20 th January 2023
Confirmed speaker biographies and photographs	Friday 24 th February 2023
Final presentation prepared	Friday 24 th March 2023